122-48

**PAD-PRINTABLE, B-STAGEABLE, EPOXY ADHESIVE**

**DESCRIPTION:** 122-48 is a pad-printable, B-Stageable, one part epoxy coating and adhesive, suitable for application by pad-printing, dipping and syringe dispensing. This system features excellent thermal stability, outstanding chemical resistance and excellent high temperature properties. Applications include adhesives, printed circuit board fabrication, advanced material composites, sealing, and high performance coatings. For applications where a lower temperature cure is required, use CMI curing agent 119-44 and follow the instructions below.

**PROPERTIES:**

- **Viscosity (cps):** 10,000-12,000
- **Glass Transition Temp. (°C):** 105
- **Dielectric Strength (volts/mil):** 425
- **Volume Resistivity (Ω-cm):** $1 \times 10^{16}$
- **Dielectric Constant (100Hz):** 4.0

**SUGGESTED HANDLING AND CURING:** Material is ready to use as received. Store frozen to maintain consistent flow properties. Allow material to warm up to room temperature before opening container. Mix container well prior to using. If necessary, 122-48 may be thinned with small amounts of CMI #113-39 (fast drying), or #114-20 (slow drying) thinners.

**STORAGE:** Shelf Life: 2 months at 25°C or 6 months at -10°C.

**INSTRUCTIONS FOR USE WITH CMI 119-44:** For every 100 parts 122-48, add 2 parts CMI 119-44 by weight and mix thoroughly until uniform. Cure 4 hours at 80°C, or 2 hours at 100°C. Pot life: 2-4 days at room temperature.

**B-STAGE PROCEDURE:** Apply adhesive to substrate. Next apply heat to advance the curing to the non-tacky stage (when cooled to room temperature). A temperature of 125°C for 2-3 minutes is required (B-Stage time is mass related). User is encouraged to experiment for optimum drying time at a given temperature. Store on release liner to prevent contamination.

**STORAGE B-STAGED FILM:** Shelf Life: 1 month @ 25°C; or 6 months @ -10°C

**BONDING PROCEDURE:** Refer to above for storage information. To use, carefully align parts to be bonded, apply uniform pressure to maintain location. Cure for 1 hour at 135°C. (Note cure times given are mass related. Timing should start after adhesive and substrates reach curing temperature.)

**SAFETY AND HANDLING:** Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

*All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.*

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